

## SIMM Sockets with Metal Latches (MICRO-EDGE) (Continued)

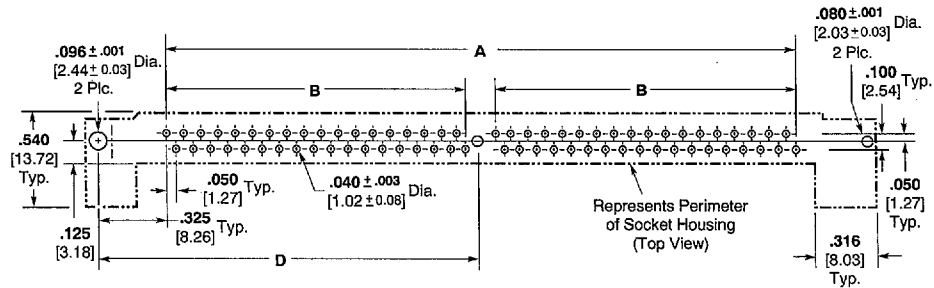
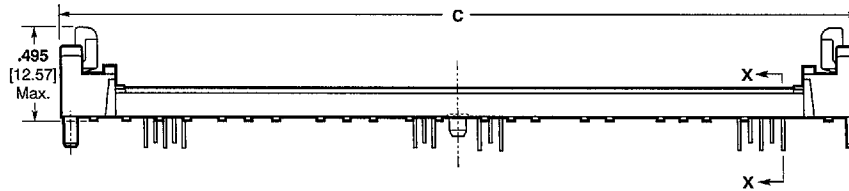
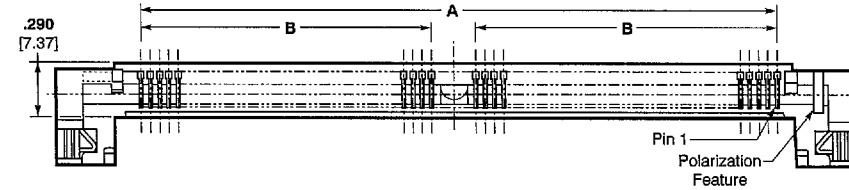
### .050 [1.27] Centerline Low Profile (22°) Single Row Connectors with Split Retention Post

#### Material and Finish

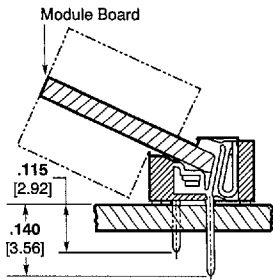
**Housing** — Liquid crystal polymer, UL 94V-0

**Contacts** — Phosphor bronze with .000200 [0.00508] min. thick tin-lead over .000050 [0.00127] min. thick nickel or .000030 [0.00076] min. thick gold on contact area and .000150 [0.0038] min. thick tin-lead on solder tails, all over .000050 [0.00127] thick nickel

**Latch** — Stainless steel



Recommended PC Board Hole Pattern



Section X-X

No. of Pos.	Dimensions				Part Numbers		Packaging Per Tube
	A	B	C	D	Tin Plate	Gold Plate	
40	2.150 54.61	.950 24.13	2.940 74.68	1.400 35.56	822110-6	822097-5	26
64	3.350 85.09	1.550 39.37	4.140 105.16	2.000 50.80	822110-1	822097-1	26
68	3.550 90.17	1.650 41.91	4.340 110.24	2.100 53.34	822110-2	822097-2	26
72	3.750 95.25	1.750 44.45	4.540 115.32	2.200 55.88	822110-3	822097-3	26
80	4.150 105.41	1.950 49.53	4.940 125.48	2.400 60.96	—	822097-4	26

Note: See page 178 for module layout.

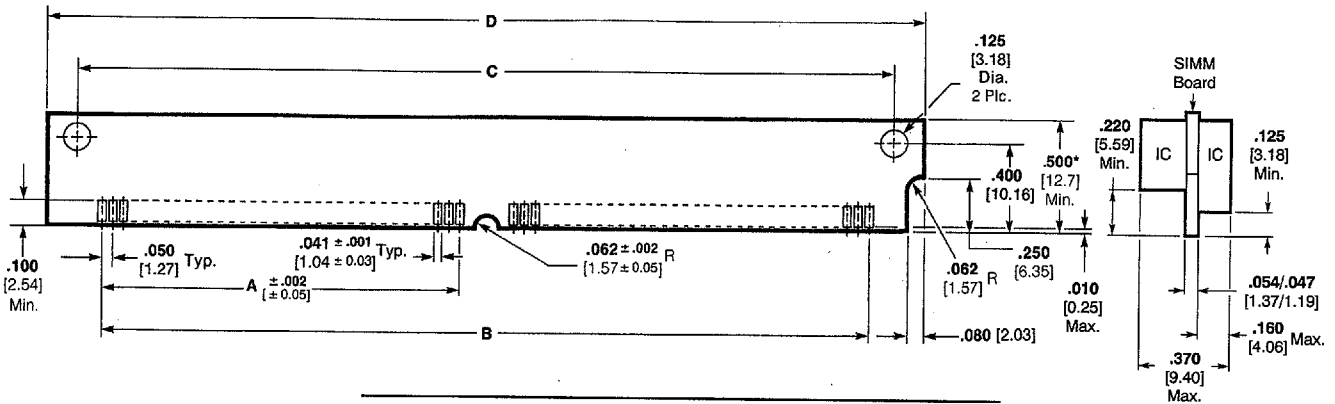
Through-Hole  
IC Sockets

## SIMM Sockets with Metal Latches (MICRO-EDGE) (Continued)



### Recommended Module Layouts

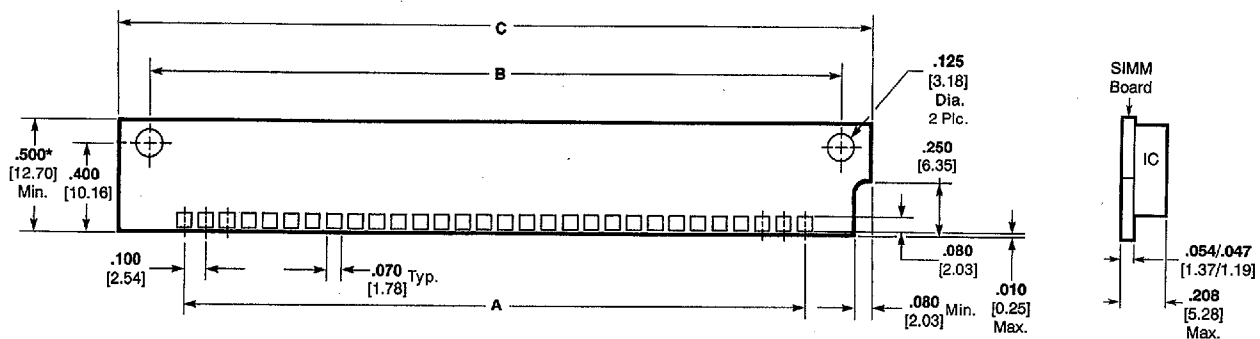
#### .050 [1.27] Centerline Module



No. of Pos.	Dimensions			
	A	B	C	D
64	1.550 39.37	3.350 85.09	3.584 91.03	3.850 97.79
68	1.650 41.91	3.550 90.17	3.784 96.11	4.050 102.87
72	1.750 44.45	3.750 95.25	3.984 101.19	4.250 107.95
80	1.950 49.53	4.150 105.41	4.384 111.35	4.650 118.11

Notes: 1. .100 x .041 [2.54 x 1.04] pad area to be free of via holes.  
2. Tabs to be electronically connected on both sides of card.  
\*Heights in excess of 1.000 [25.4], consult AMP.

#### .100 [2.54] Centerline Module Layout



No. of Pos.	Dimensions		
	A	B	C
22	2.100 53.34	2.434 61.82	2.700 68.58
30	2.900 73.66	3.234 82.14	3.500 88.90
35	3.400 86.36	3.734 94.84	4.000 101.60
40	3.900 99.06	4.234 107.54	4.500 114.30
42	4.100 104.14	4.434 112.62	4.700 119.38

Notes: 1. .080 x .070 [2.03 x 1.78] pad area to be free of via holes.  
2. Tabs to be electronically connected on both sides of card.  
\*Heights in excess of 1.000 [25.4], consult AMP.

Through-Hole IC Sockets